

# Low Voltage Quad 2-Input NAND Gate

# **74LVX00**

# **General Description**

The LVX00 contains four 2-input NAND gates. The inputs tolerate voltages up to 6.5 V allowing the interface of 5 V systems to 3 V systems.

#### **Features**

- Input Voltage Level Translation from 5 V to 3 V
- Ideal for Low Power/Low Noise 3.3 V Applications
- Guaranteed Simultaneous Switching Noise Level and Dynamic Threshold Performance

# **Logic Symbol**

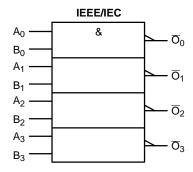


Figure 1. Logic Symbol

# **ABSOLUTE MAXIMUM RATINGS**

Symbol	Para	Rating	
V <sub>CC</sub>	Supply Voltage		–0.5 V to +6.5 V
I <sub>IK</sub>	DC Input Diode Co	urrent, $V_I = -0.5 \text{ V}$	–20 mA
V <sub>I</sub>	DC Input Voltage		–0.5 V to 6.5 V
lok	DC Output	$V_0 = -0.5 \text{ V}$	–20 mA
	Diode Current	$V_{O} = V_{CC} + 0.5 \text{ V}$	+20 mA
V <sub>O</sub>	DC Output Voltage	9	-0.5 V to V <sub>CC</sub> + 0.5 V
Io	DC Output Source	or Sink Current	±25 mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground	±50 mA	
TSTG	Storage Temperat	–65°C to +150°C	
P <sub>D</sub>	Power Dissipation		833 mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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# **MARKING DIAGRAM**



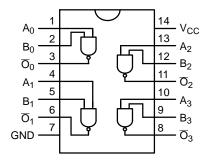
XXX = Specific Device Code
A = Assembly Location
L = Wafer Lot

L = Wafer Lot Y = Year

W = Work Week ■ Pb–Free Package

(Note: Microdot may be in either location)

# **CONNECTION DIAGRAM**



#### PIN DESCRIPTION

Pin Names	Description
A <sub>n</sub> , B <sub>n</sub>	Inputs
$\overline{O}_n$	Outputs

# **ORDERING INFORMATION**

See detailed ordering and shipping information on page 3 of this data sheet.

# 74LVX00

# **RECOMMENDED OPERATING CONDITIONS** (Note 1)

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage	2.0 V to 3.6 V
VI	Input Voltage	0 V to 5.5 V
V <sub>O</sub>	Output Voltage	0 V to V <sub>CC</sub>
T <sub>A</sub>	Operating Temperature	-40°C to +85°C
$\Delta t / \Delta V$	Input Rise and Fall Time	0 ns/V to 100 ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

# DC ELECTRICAL CHARACTERISTICS

		V <sub>CC</sub>			T <sub>A</sub> = +25°C		$T_A = -40^{\circ}$	C to +85°C	
Symbol	Parameter	(V)	Conditions	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	HIGH Level Input	2.0		1.5	-	_	1.5	_	V
	Voltage	3.0		2.0	-	_	2.0	_	
		3.6		2.4	-	-	2.4	-	
V <sub>IL</sub>	LOW Level Input	2.0		-	-	0.5	-	0.5	V
	Voltage	3.0		-	-	0.8	-	0.8	
		3.6		-	-	0.8	-	0.8	
V <sub>OH</sub>	HIGH Level Output	2.0	$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OH} = -50 \mu A$	1.9	2.0	-	1.9	-	V
	Voltage	3.0	$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OH} = -50 \mu A$	2.9	3.0	-	2.9	-	
			$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OH} = -4$ mA	2.58	-	-	2.48	-	
V <sub>OL</sub>	LOW Level Output	2.0	$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OL} = 50 \mu A$	-	0.0	0.1	-	0.1	V
	Voltage	3.0	$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OL} = 50 \mu A$	-	0.0	0.1	-	0.1	
			$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OL} = 4mA$	-	-	0.36	-	0.44	
I <sub>IN</sub>	Input Leakage Current	3.6	V <sub>IN</sub> = 5.5 V or GND	-	-	±0.1	_	±1.0	μΑ
Icc	Quiescent Supply Current	3.6	$V_{IN} = V_{CC}$ or GND	_	_	2.0	_	20.0	μΑ

# NOISE CHARACTERISTICS (Note 2)

				T <sub>A</sub> = 25°C		
Symbol	Parameter	V <sub>CC</sub> (V)	C <sub>L</sub> (pF)	Тур	Limit	Unit
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>	3.3	50	0.3	0.5	V
$V_{OLV}$	Quiet Output Minimum Dynamic V <sub>OL</sub>	3.3	50	-0.3	-0.5	V
$V_{IHD}$	Minimum HIGH Level Dynamic Input Voltage	3.3	50	-	2.0	V
$V_{ILD}$	Maximum LOW Level Dynamic Input Voltage	3.3	50	ı	0.8	V

<sup>2.</sup> Input  $t_r = t_f = 3 \text{ ns}$ 

# 74LVX00

# **AC ELECTRICAL CHARACTERISTICS**

				$T_A = 25^{\circ}C$ $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			C to +85°C		
Symbol	Parameter	V <sub>CC</sub> (V)	C <sub>L</sub> (pF)	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay Time	2.7	15	-	5.4	10.1	1.0	12.5	ns
			50	-	7.9	13.6	1.0	16.0	
		3.3 ±0.3	15	_	4.1	6.6	1.0	7.5	
			50	_	6.6	9.7	1.0	11.0	
t <sub>OSLH</sub> ,	Output to Output Skew (Note 3)	2.7	50	_	_	1.5	-	1.5	ns
toshl		3.3		_	-	1.5	_	1.5	

<sup>3.</sup> Parameter guaranteed by design  $t_{OSLH} = |t_{PLHm} - t_{PLHn}|$ ,  $t_{OSHL} = |t_{PHLm} - t_{PHLn}|$ 

# **CAPACITANCE**

		$T_{A} = 25^{\circ}C$ $T_{A} = -40^{\circ}$		$T_A = -40^{\circ}$	c to +85°C		
Symbol	Parameter	Min	Тур	Max	Min	Max	Unit
C <sub>IN</sub>	Input Capacitance	-	4	10	-	10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note )	-	19	-	_	-	pF

<sup>4.</sup> CPD is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:

$$I_{\text{CC(opr.)}} = \frac{C_{\text{PD}} \times V_{\text{CC}} \times f_{\text{IN}} \times I_{\text{CC}}}{4 \text{ (per Gate)}}$$

# **ORDERING INFORMATION**

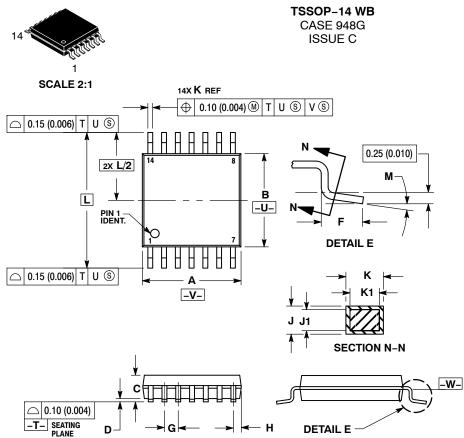
Device Order Number	Marking	Package	Shipping <sup>†</sup>
74LVX00MTCX	LVX 00	TSSOP-14 WB (Pb-Free, Halide Free)	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*-</sup>Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

**DATE 17 FEB 2016** 





- NOTES.

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

  6. TERMINAL NUMBERS ARE SHOWN FOR DEFERENCE ONLY
- REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40		0.252 BSC		
М	0 °	8 °	0 °	8 °	

# **GENERIC MARKING DIAGRAM\***



= Assembly Location

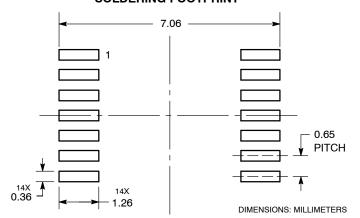
= Wafer Lot L = Year = Work Week W

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

# **RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	TSSOP-14 WB		PAGE 1 OF 1		

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